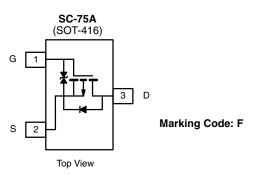


Vishay Siliconix

P-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS(min.)} (V)	R_{DS(on)} (Ω)	V _{GS(th)} (V)	I _D (mA)			
- 60	4.0 at V _{GS} = - 10 V	- 1 to 3.0	- 190			



Ordering Information: Si1021R-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFETs
- High-Side Switching
- Low On-Resistance: 4 Ω
- Low Threshold: 2 V (typ.)
- Fast Switching Speed: 20 ns (typ.)
- Low Input Capacitance: 20 pF (typ.)
- Miniature Package
- ESD Protected: 2000 V
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Battery Operated Systems
- Power Supply Converter Circuits
- Solid-State Relays

BENEFITS

- Ease in Driving Switches
- Low Offset Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Easily Driven without Buffer
- Small Board Area

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)							
Parameter		Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	- 60	v			
Gate-Source Voltage		V _{GS}	± 20	7 V			
Continuous Drain Current (T _{.1} = 150 °C) ^a	T _A = 25 °C	- I _D	- 190				
Continuous Drain Current $(T_j = 150^{\circ} C)$	T _A = 85 °C		- 135	mA			
Pulsed Drain Current ^b		I _{DM}	- 650	-			
Power Dissipation ^a	T _A = 25 °C	Р	250	mW			
	T _A = 85 °C	P _D	130	11100			
Maximum Junction-to-Ambient ^a		R _{thJA}	500	°C/W			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C			

Notes:

a. Surface mounted on FR4 board.

b. Pulse width limited by maximum junction temperature.



Si1021R

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = -10 \mu A$	- 60			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -0.25 \text{ mA}$	- 1		- 3.0		
Gate-Body Leakage		$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 10	μA	
	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 10 V		± 200			
		$V_{DS} = 0 \text{ V}, \text{ V}_{GS} = \pm 10 \text{ V}, \text{ T}_{J} = 85 ^{\circ}\text{C}$			± 500		
		$V_{DS} = 0 V, V_{GS} = \pm 5 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = -50 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 25		
	IDSS	V_{DS} = - 50 V, V_{GS} = 0 V, T_{J} = 85 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V_{DS} = -10 V, V_{GS} = - 4.5 V	- 50				
		V _{DS} = -10 V, V _{GS} = - 10 V	- 600			mA	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 25 mA			8	Ω	
		V _{GS} = - 10 V, I _D = - 500 mA			4		
		V_{GS} = - 10 V, I_{D} = - 500 mA, T_{J} = 125 °C			6	}	
Forward Transconductance	9 _{fs}	V _{DS} = - 10 V, I _D = - 100 mA	80			mS	
Diode Forward Voltage ^a	V _{SD}	V _{DS} = - 200 mA, V _{GS} = 0 V	80			V	
Dynamic	•						
Total Gate Charge	Qg			1.7		nC	
Gate-Source Charge	Q _{gs}	V_{DS} = - 30 V, V_{GS} = - 15 V, $I_D \cong$ - 500 mA		0.26			
Gate-Drain Charge	Q _{gd}			0.46			
Input Capacitance	C _{iss}			23		pF	
Output Capacitance	C _{oss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		10			
Reverse Transfer Capacitance	C _{rss}	1		5			
Switching ^b					I		
Turn-On Time	t _{ON}	V _{DD} = - 25 V, R _I = 150 Ω,		20		ns	
Turn-Off Time	tOFF	$I_D \cong$ - 200 mA, V_{GEN} = - 10 V, R_g = 10 Ω		35			

Notes:

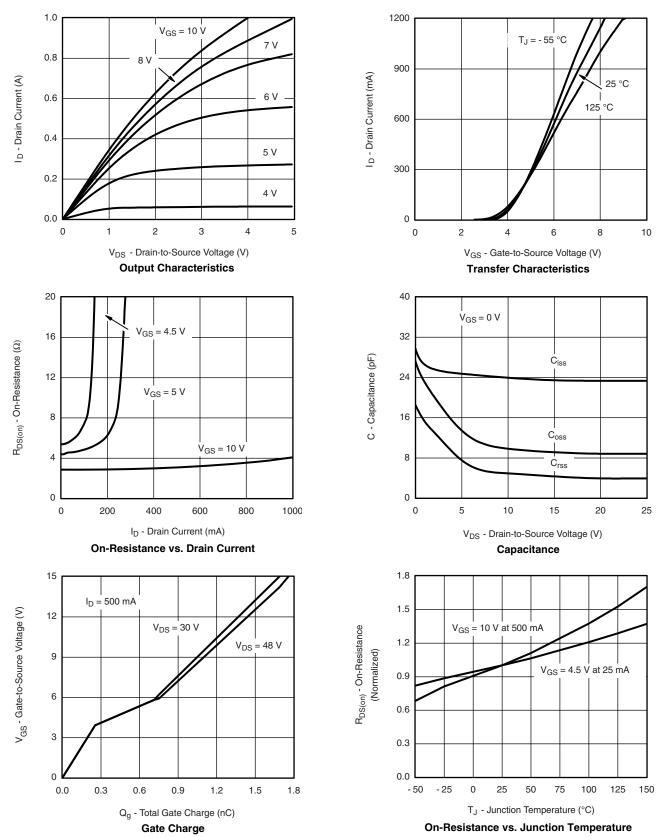
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



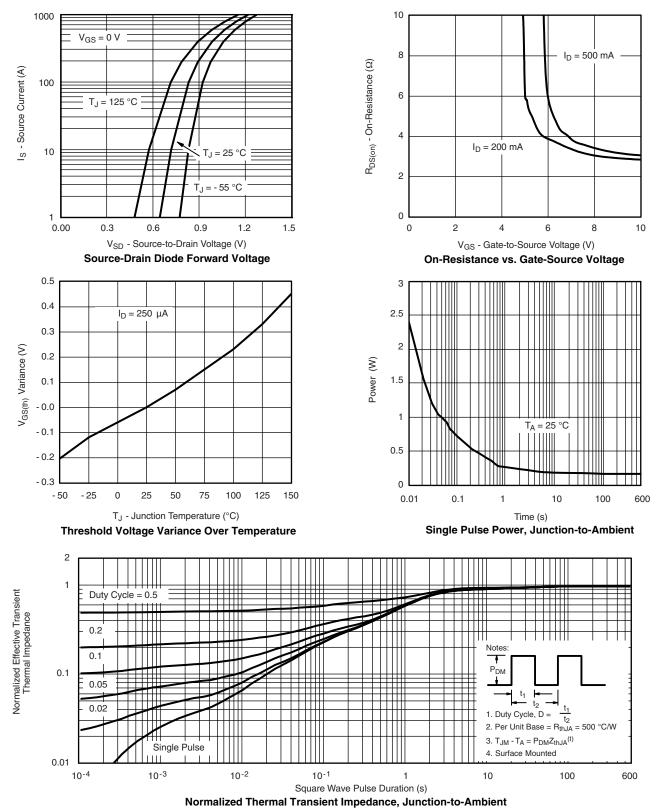
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



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TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?71410.



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